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FIG. 1

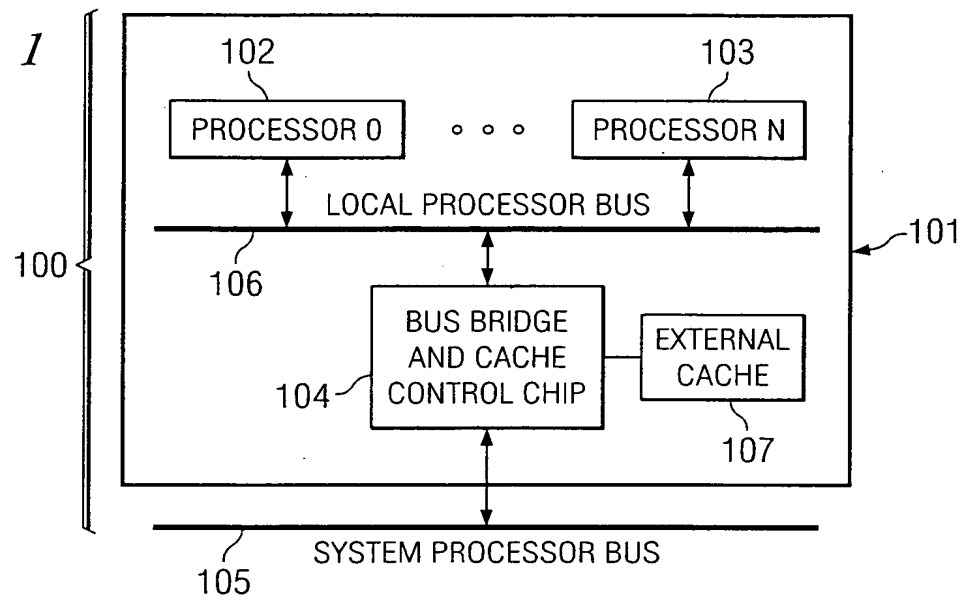
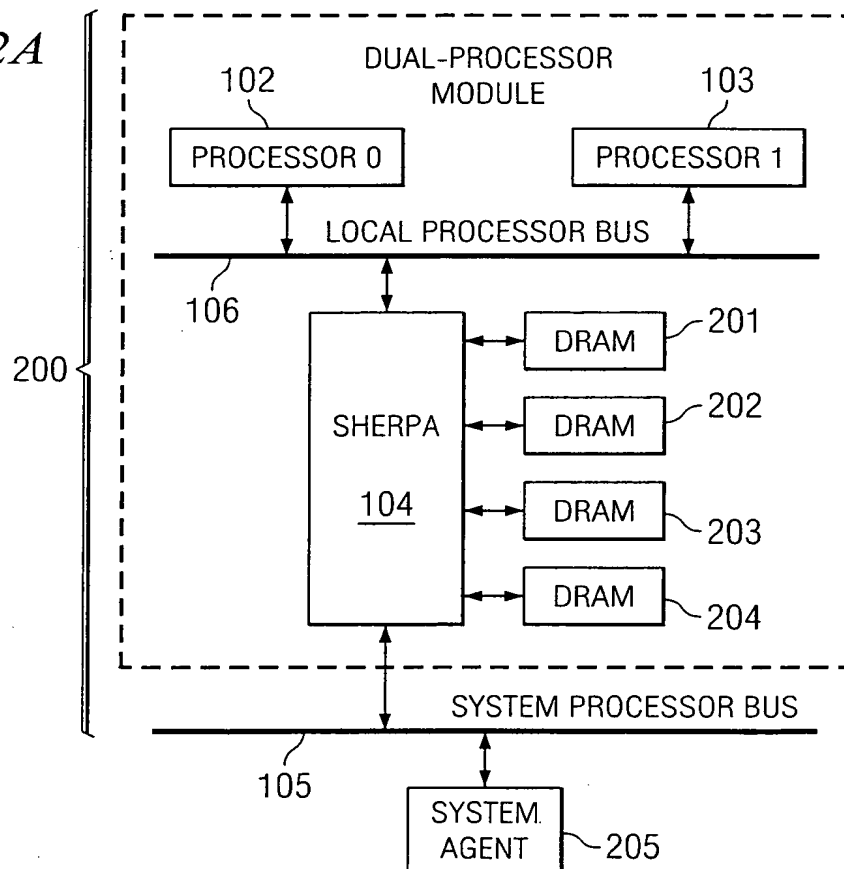
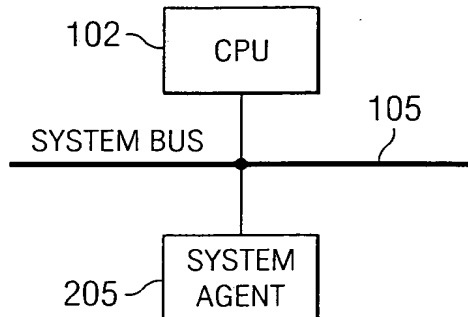


FIG. 2A

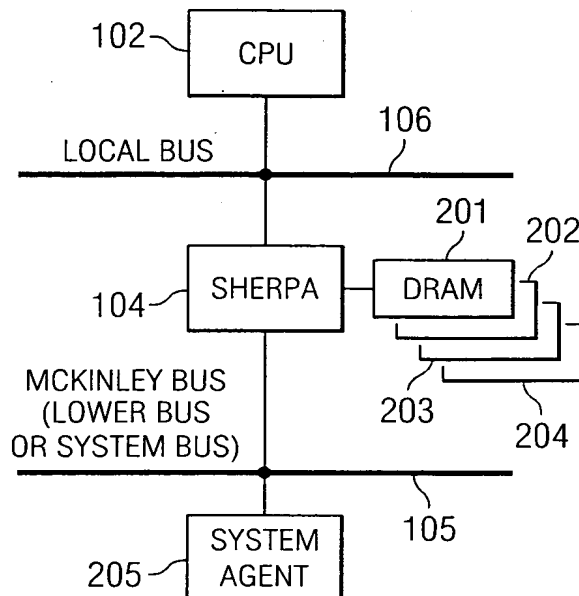


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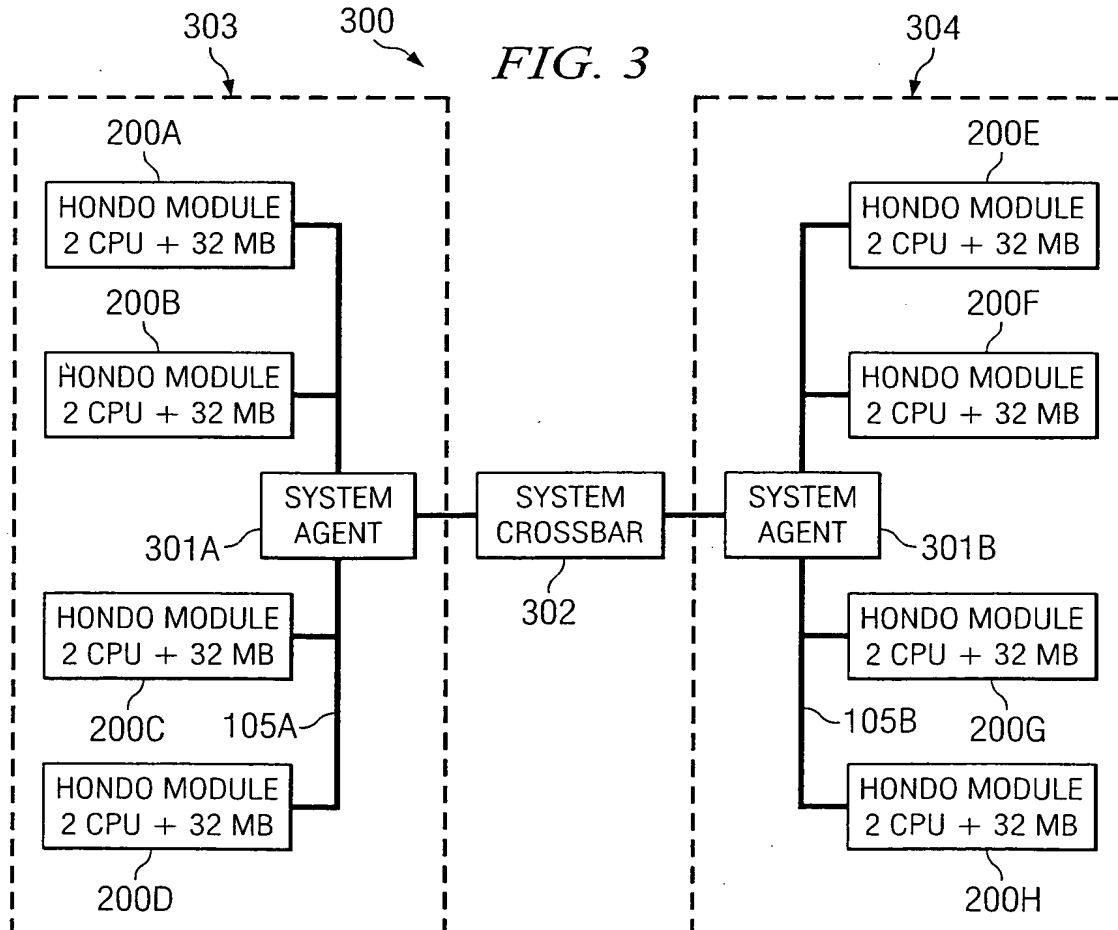
**FIG. 2B**  
(PRIOR ART)



**FIG. 2C**

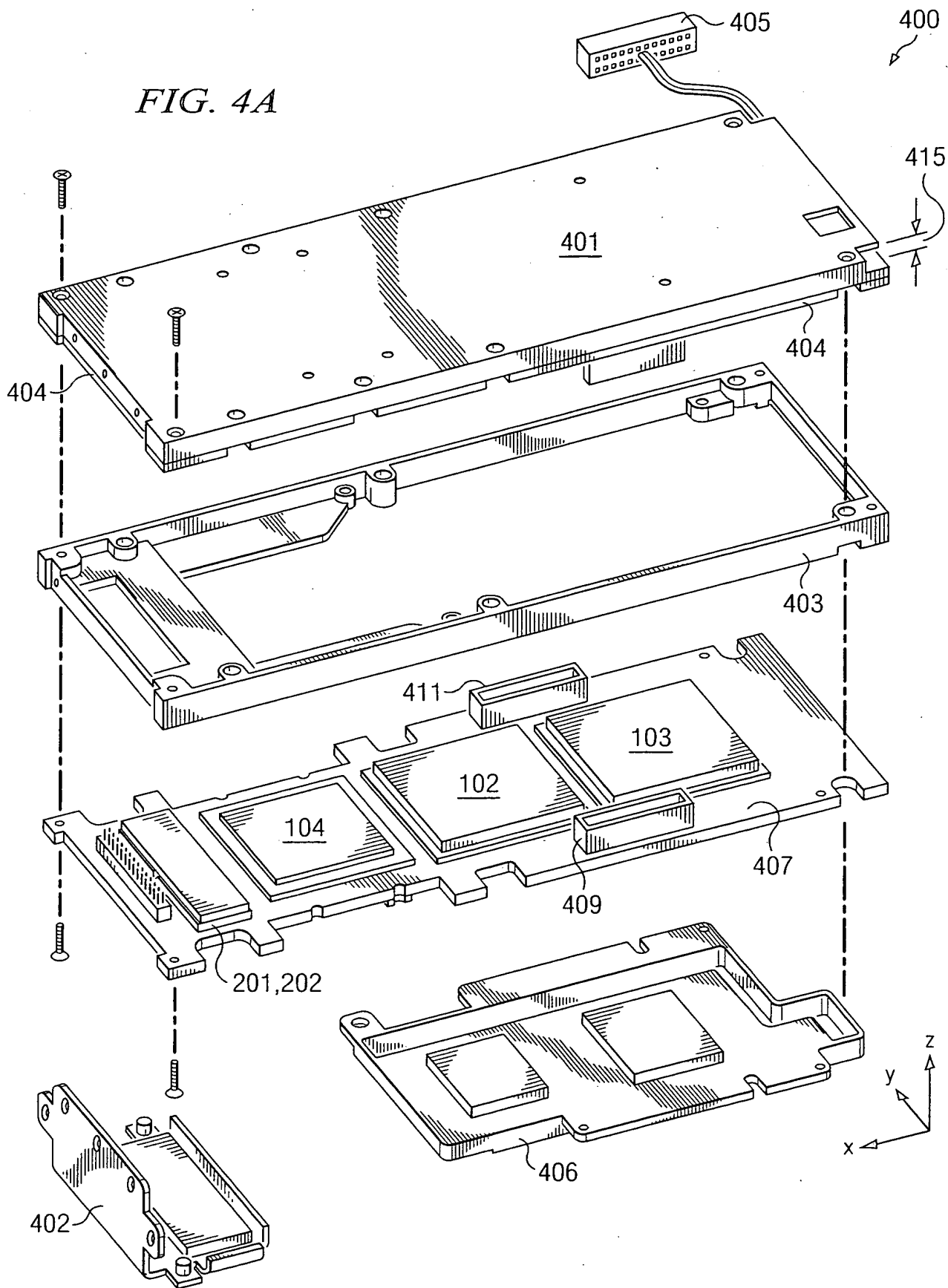


**FIG. 3**

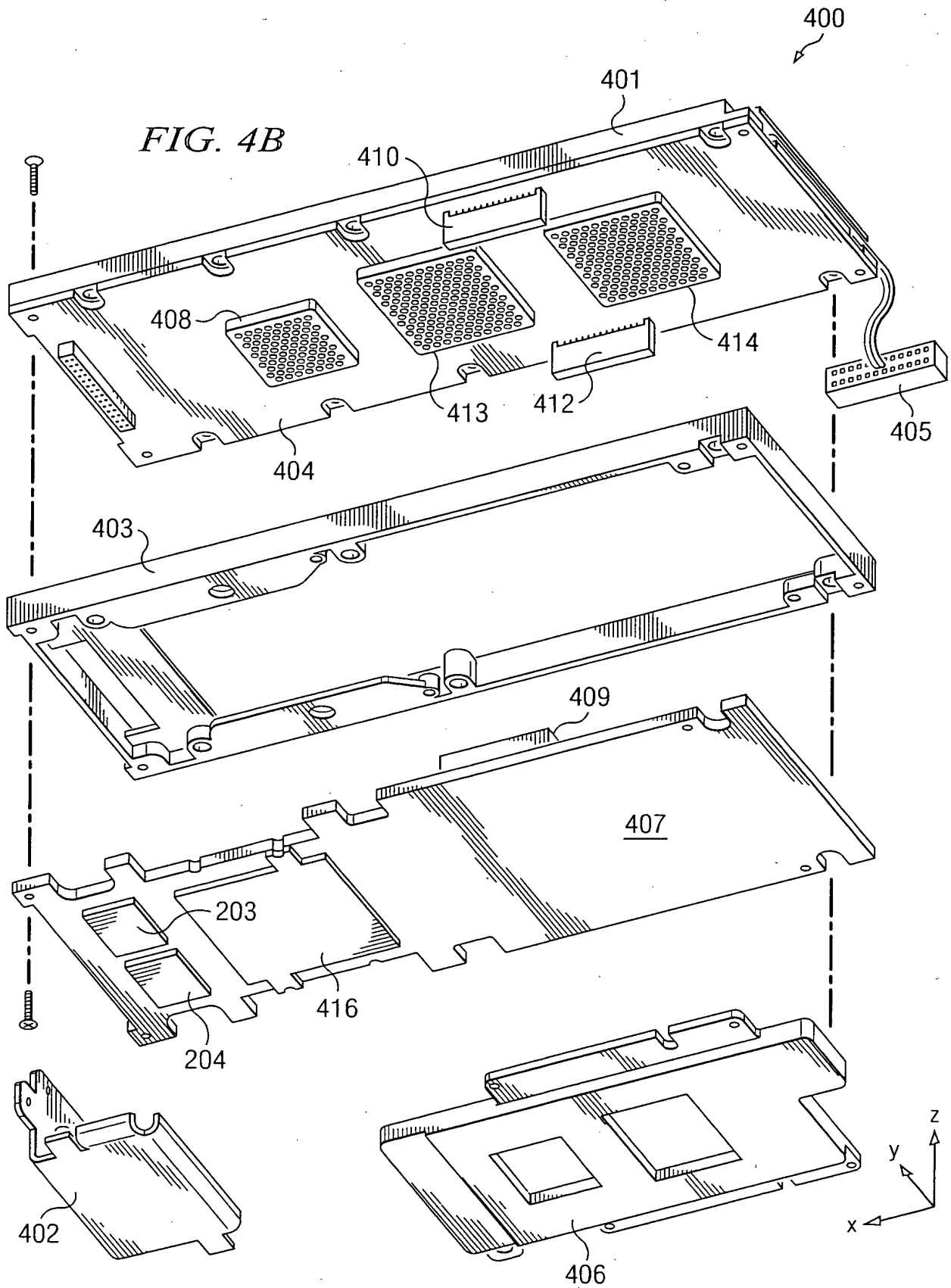


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FIG. 4A



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FIG. 5

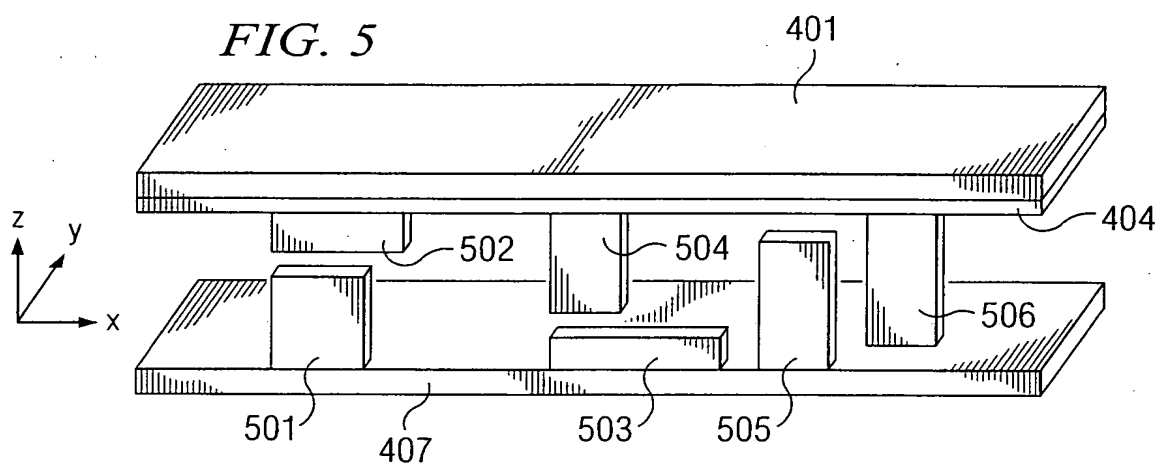


FIG. 6

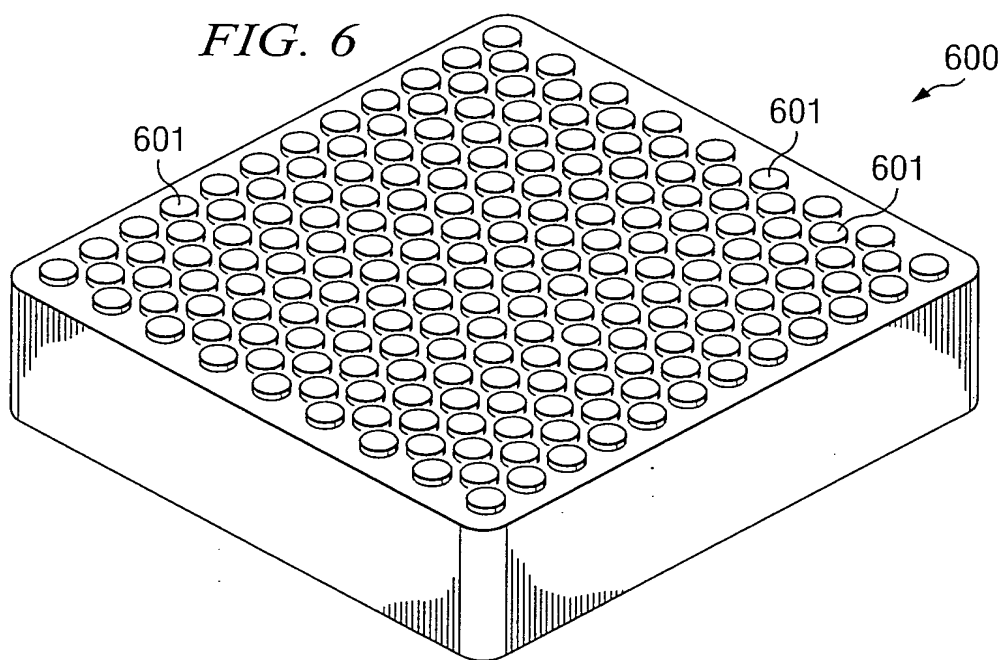
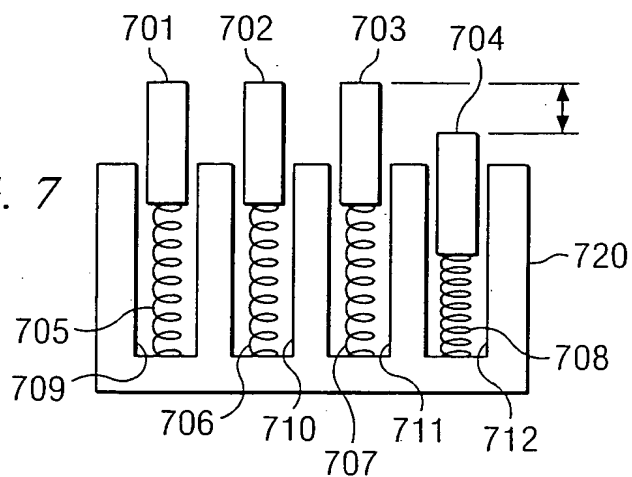
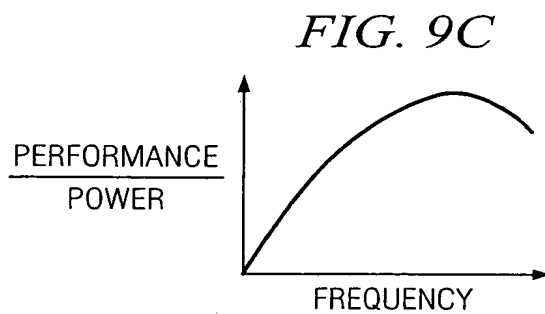
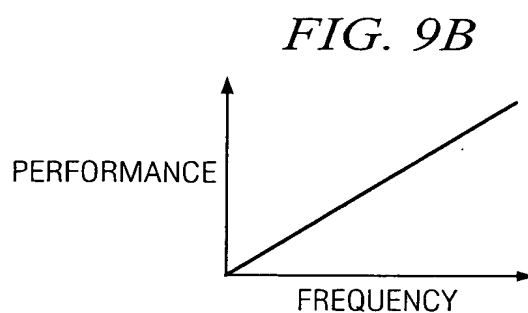
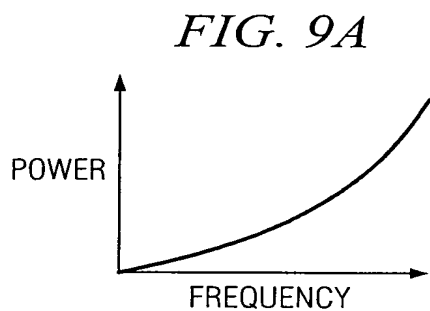
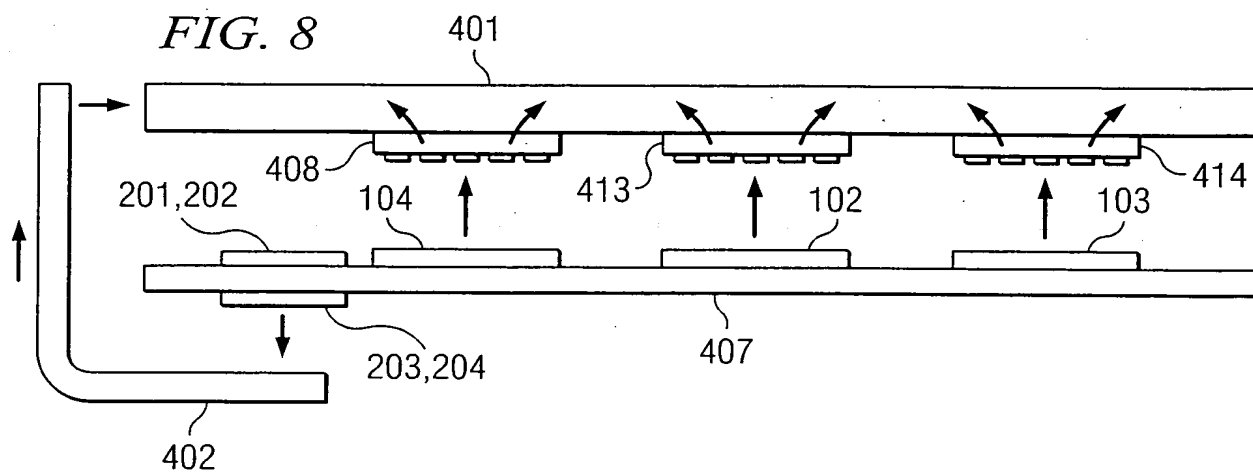


FIG. 7



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FIG. 10

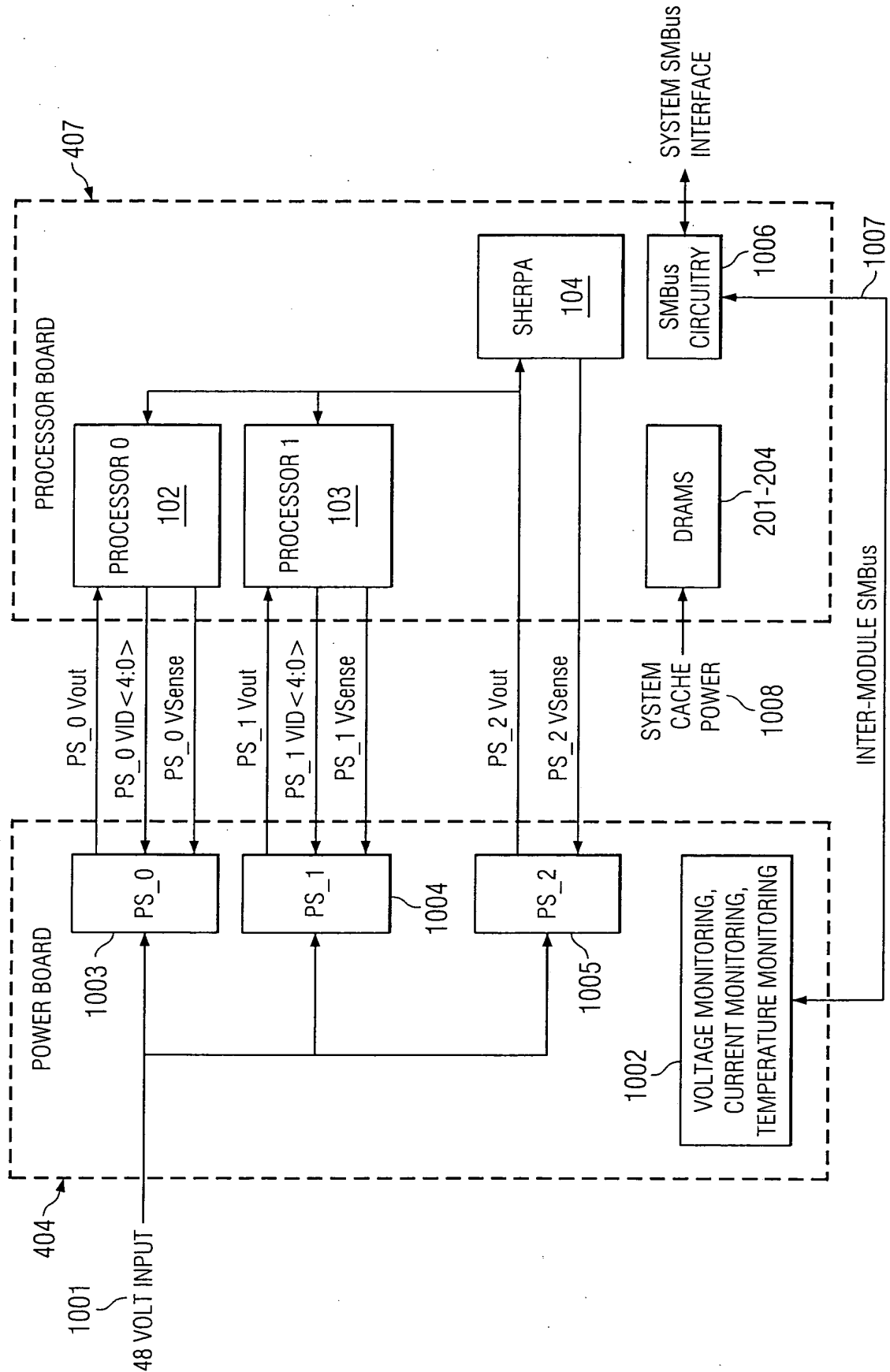


FIG. 12A is a cross-sectional view of a multi-layered substrate. The substrate consists of several layers: SURFACE LAYER, MICRO-VIA LAYER 1, MICRO-VIA LAYER 2, LAYER 3, LAYER 4, and LAYER 5. A vertical conductive structure 1201 is formed through the SURFACE LAYER and MICRO-VIA LAYER 1. A horizontal conductive layer 1202-1204 is formed on the SURFACE LAYER. A horizontal conductive layer 1220 is formed on MICRO-VIA LAYER 2. A horizontal conductive layer 1230 is formed on MICRO-VIA LAYER 2. A horizontal conductive layer 1205-1207 is formed on LAYER 3. A vertical conductive structure 1208 is formed through LAYER 3, LAYER 4, and LAYER 5. The layers are separated by horizontal lines, and the conductive structures are indicated by hatched patterns.



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FIG. 12B

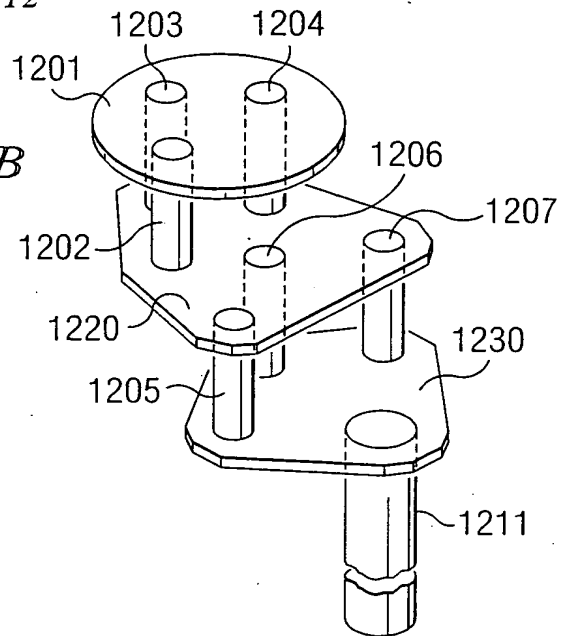
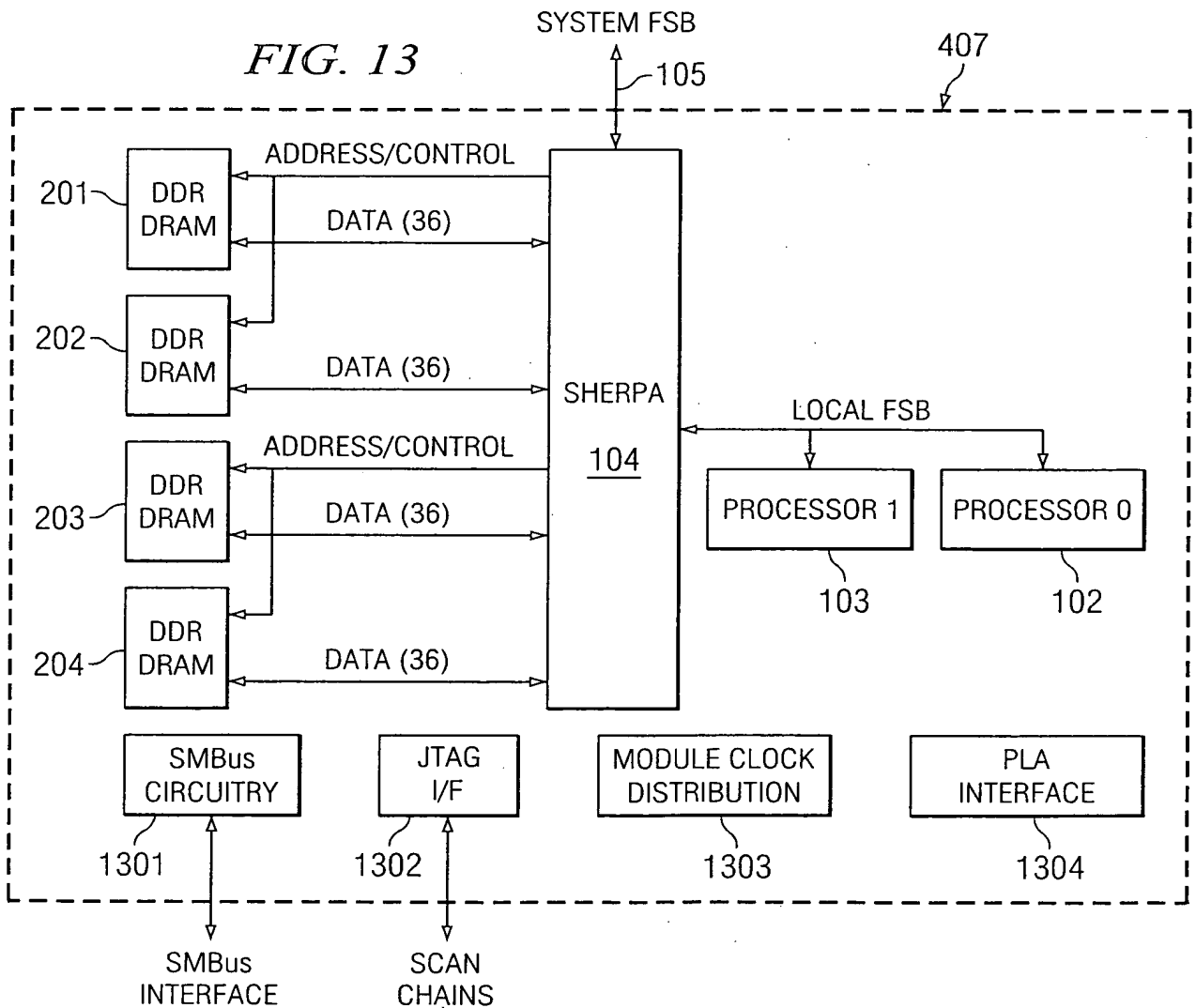


FIG. 13



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FIG. 14

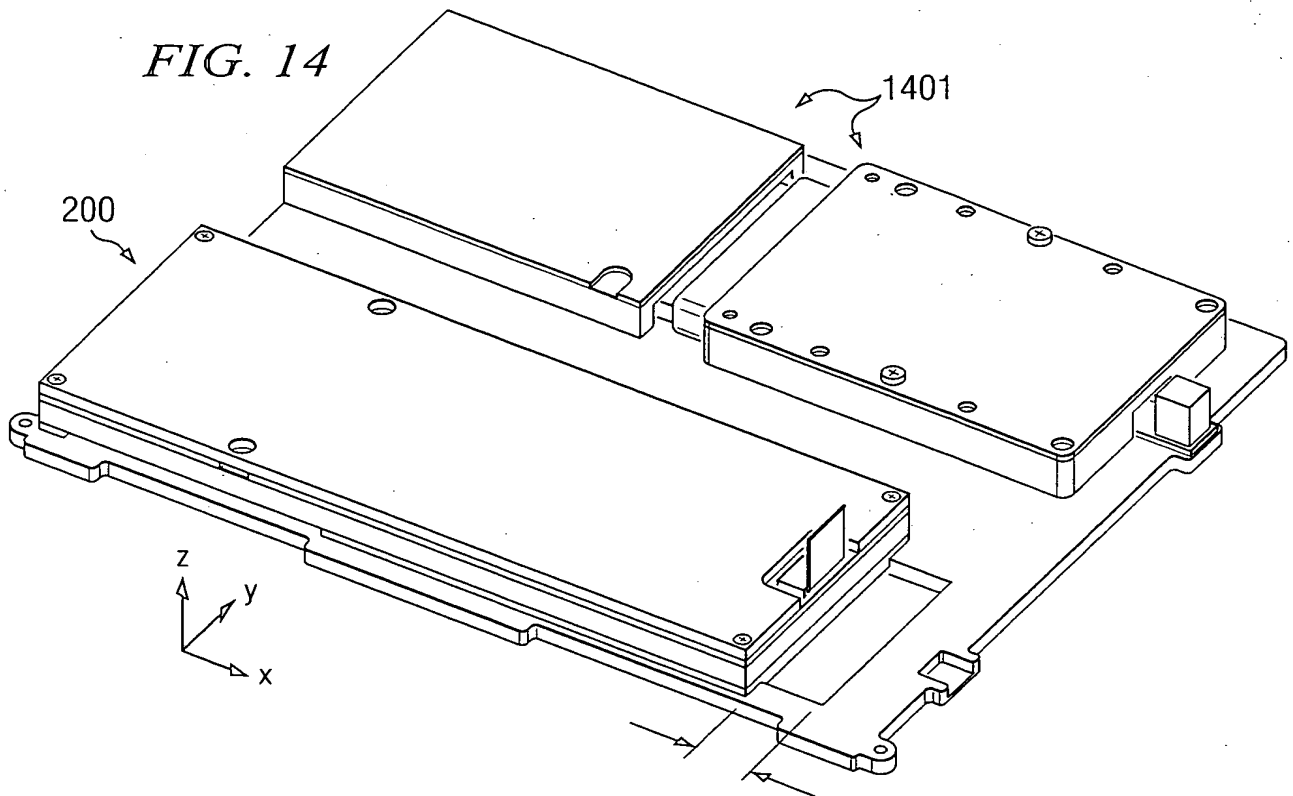
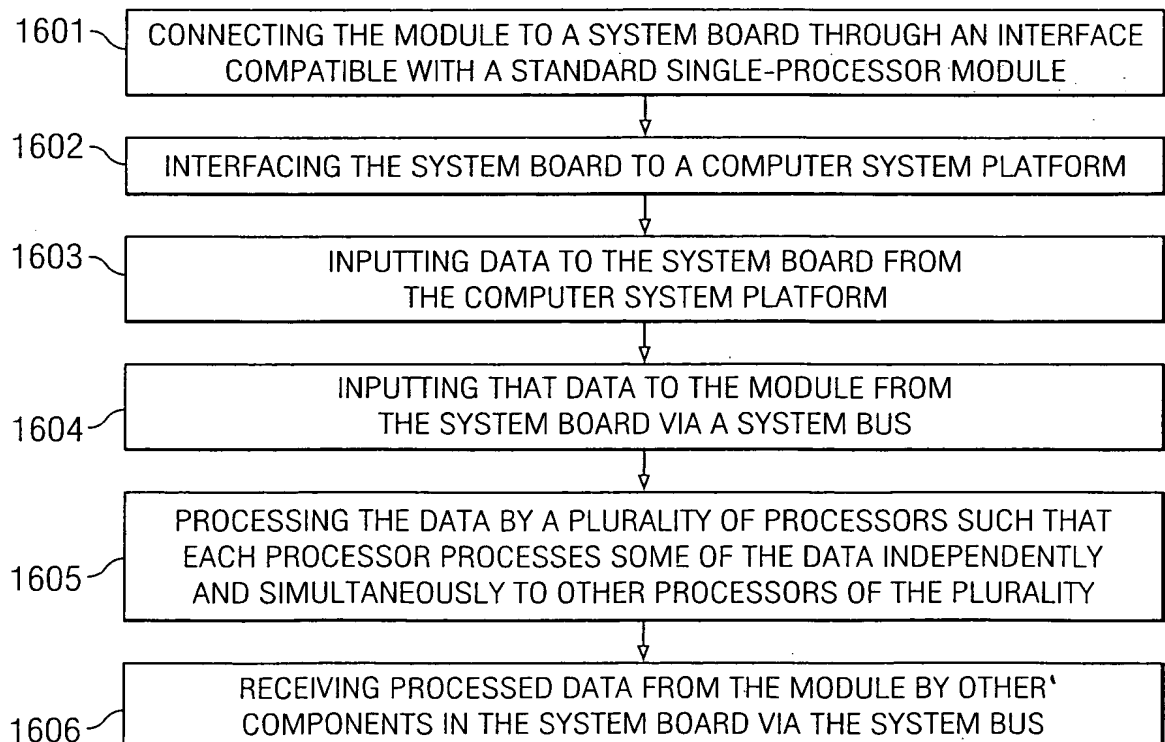
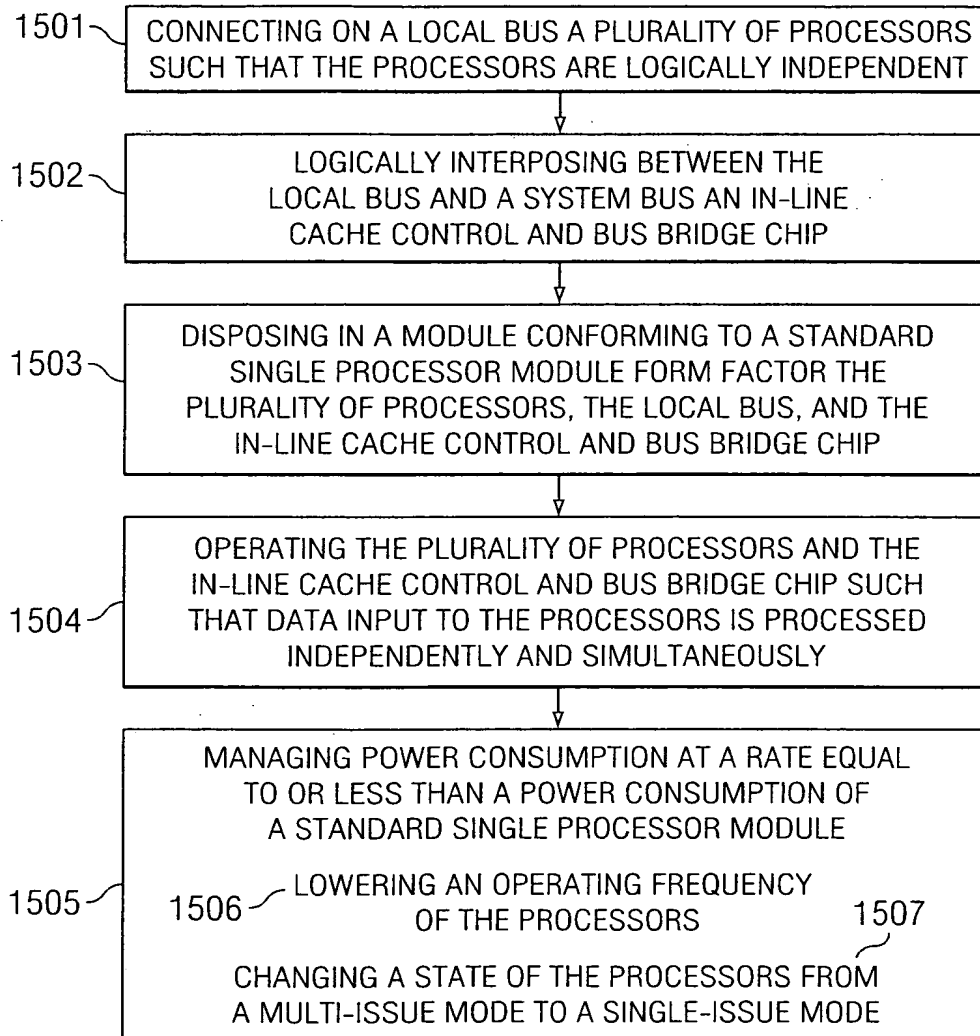


FIG. 16



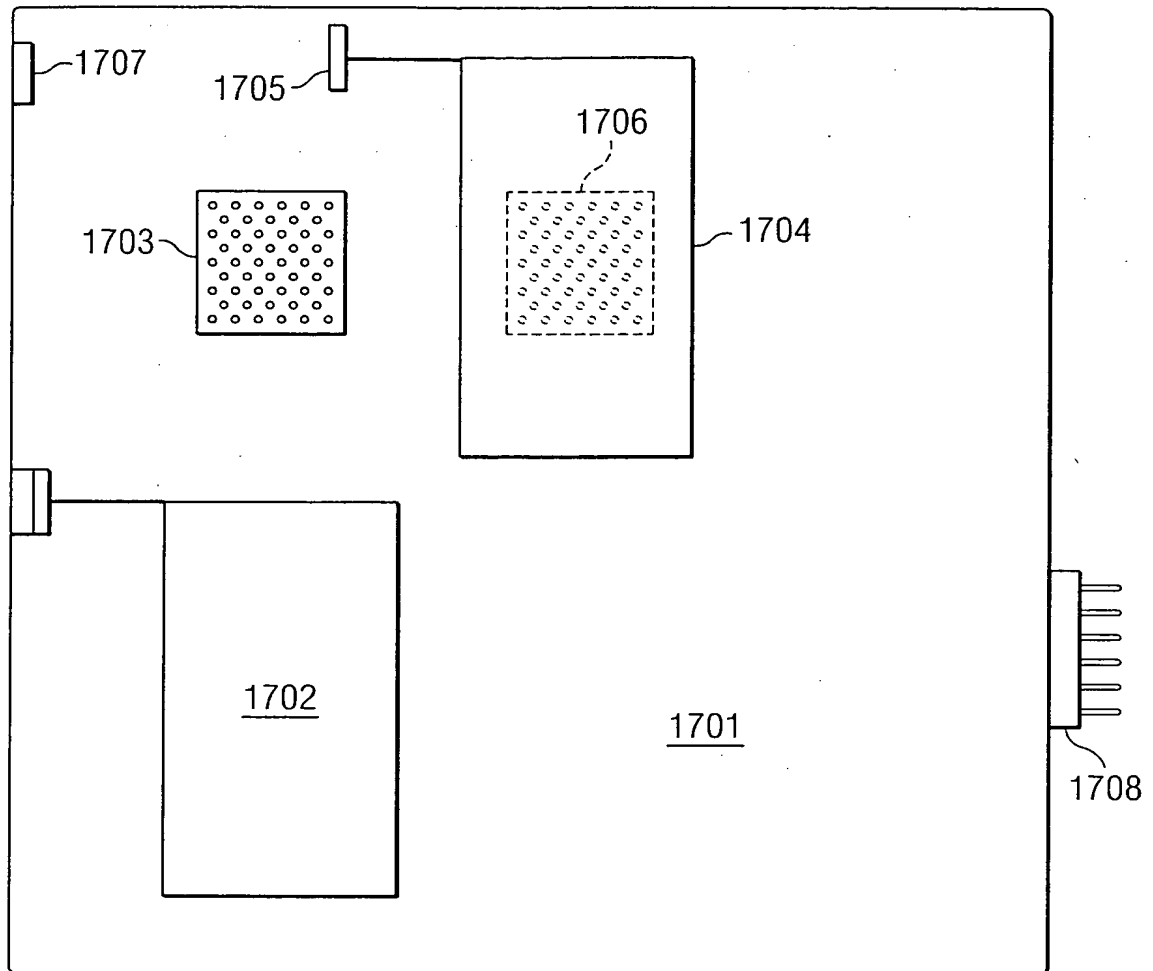
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*FIG. 15*

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*FIG. 17A*



*FIG. 17B*

